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(54) **Title:** PROCESS FOR REMOVING BOND FILM FROM CAVITIES IN PRINTED CIRCUIT BOARDS

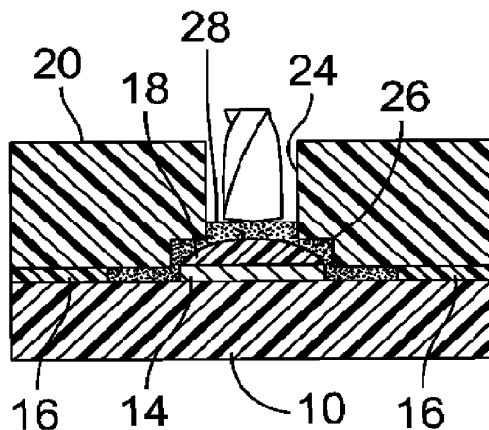


FIG. 5

(57) **Abstract:** A process of fabricating an electromagnetic circuit includes providing a first sheet of dielectric material including a top surface having at least one conductive trace and depositing a solder bump on the at least one conductive trace. The process further includes applying a second sheet of dielectric material to the first sheet of dielectric material with bond film sandwiched in between, the second sheet of dielectric material having a through-hole providing access to the solder bump. The process further includes bonding the first and second dielectric materials to one another and removing bond film resin from the solder bump. The process further includes machining the solder bump by the drilling or milling process to achieve a desired amount of solder in the solder bump.

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